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Experimental Investigation of Micro fins for Heat Transfer Enhancement by using Copper, Aluminum and Aluminum with Paint Coating as a Micro fins

Sayali R. Bhalerao[1]
sayali16sb@gmail.com

R. R. Arakerimath[2]
rrarakerimath@gmail.com

[1,2]Department of Mechanical Engineering,
G. H. Raisoni College of Engineering and Management,
Pune, India

Abstract— **Computer applications have lately embraced micro technologies. Micro-technologies are now being used in many cooling systems, but the thermal efficiency of micro-fins under forced convective heat transfer conditions is still a little bit of an unknown. Despite previous research, micro finned array architecture cannot be optimally optimized based on Heat transfer coefficients and fine geometry correlations. This study first time integrates a variety of heat sink measurements to offer an overview of microfin behavior. Mass-specific heat transfer coefficient of penalties and efficiency of the fins. Results from an original experiment are combined in this process with the most recent data available in the literature. Microfins are always determined to be favorable in terms of material utilization. There may be advantages to using these light micro fins in applications that need a heat sink to have a minimum weight. In addition, the direction has a modest influence.**

Keywords— Heat transfer, Micro fin array, Reynolds numbers, forced convection, aluminum paint, micro-fin, heat transfer, heat sink, cpv, cooling, micro heat sinks.

I. Introduction

There are a variety of fins that are used to improve heat transfer from a structure to the fluid surrounding it. Numerous studies have studied the use of fins which are now being used for several different applications, such as telecommunications, manufacturing processes which electricity generation. Fins are known as passive coolers in natural convection, as they do not need feedback of mechanical or electrical power. Fins work by leveraging both a thermal gradient's natural convective motion of a fluid and the radiated heat transfer [1,6]. In general, passive coolers are considered more robust and less vulnerable to cooling failures [2,7] than active coolers, which still allow additional input energy to work. Industries and customers are also for manufacturing goods that are more effective, more lightweight and cheaper. Because of the improved efficiency obtained and the small space and resource needed relative to macro-scaled approaches, micro technologies have gained much attention in this context over the last decades. Micro-cooling systems, particularly micro-finned arrays under forced convection conditions, have been the subject of much research. The thermal efficiency of different finish forms has been studied in several laboratory studies.. Since of the larger surface area

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and better heat transfer coefficient, micro pin fins have greater heat dissipation per unit mass than micro plate fins [3]. Pin fin optimizes resource efficiency with surface area rise. It has been found in laboratory experiments on various forms of microfin configuration and shapes that the square microfin has the greatest transfer of boiling heat. The micro-fin is developed for specific fineness spacing on metal materials by means of wire-cut electric discharge machining (WEDM). The processed microfin is treated with Al pigment, and its effects on the transmission of convective heat are observed.

Yevov Peles et al. [3,8-10] examined the phenomena of heat transfer and pressure decrease over a number of micropin fins. They derived a simple expression for the total thermal resistance, and experimentally validated the same. Geometric as well as thermo-hydraulic parameters are discussed which influence the overall thermal resistance. A pin fin heat sink has been found to give very low thermal resistances. The values of thermal resistance are contrasted with those obtained in convective flows in micro channels. For certain situations, the rise in the flow temperature results of a thermal resistance to convection was also found, though it is slightly lower than the average thermal resistance. It is hypothesized that heat sinks are a very efficient heat transfer mode with forced convection over veiled micro fins.

Pin fin channels with permeable pin fins were statistically investigated for forced convective heat transfer. The Forchheimer-Brinkman extended Darcy model and the two equation-energy model are used to determine heat transport in porous materials. Air and water are used to analyse cold fluids in detail, as well as Reynolds number, pore depth, and pin fin shape. Pin fin porous channel heat transfer efficiency has been found to be much higher than solid pin fin channels.. Pore density is observed to have a substantial impact. There are pressure and heat flux increases with decreasing PPI in porous pin-fine channels, and the average total heat transfer efficiency for air and water cases is observed at PPI-20. The heat transmission efficiency of the long elliptic porous pin-fin channels was determined to be the greatest.. [4,11].

The effects of pin spacing on heat transfer and pressure loss through pin fine arrays for Reynolds numbers ranging from 5000 to 30000 were studied. Overall, it was determined that span wise pin spacing had a lower influence on array pressure loss than stream wise pin spacing, whereas stream wise pin spacing had a considerable effect on array heat transfer [5,13].

II. MICRO FINS ARRAY

Microfin array heat sinks tend to be an important method for cooling small electronic devices. This heat sinks are efficient and noiseless cooling systems which do not need a great deal of power to operate. A traditional heat sink for the microfin collection is made of multiple rectangular fins with micro dimensions placed on a flat plate. Higher thermal output in high heat flux and critical equipment like aerospace, microelectronics etc. And technology evolving exponentially in recent decades, Higher power output in high flux power and critical machinery such as aerospace, microelectronics etc. And in recent decades technology is developing rapidly, Micro-fins can be used in different areas, such as power electronics, photovoltaic concentration, and LED. Though micro-technologies were commonly used in cooling.

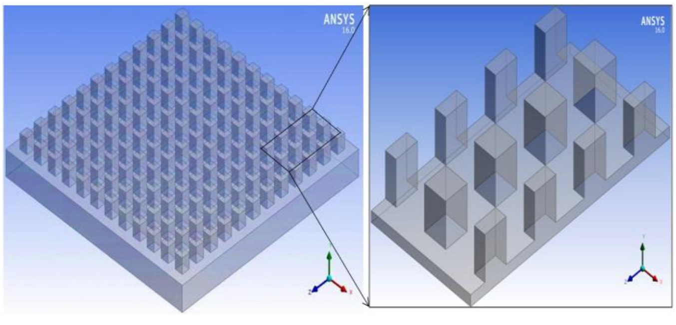

Figure 1. Catia-V5-R16 created a typical 3-D depiction of a microfin array

III. RESULT AND DISCUSSION

- Figure 1 displays the coefficient of convectible heat transfer plotted at 3.75 mm spacing for coated and uncoated test sections against the temperature differential. Basing on the figure 2 It is clear that the coefficient of convective heat transfer for aluminum paint coated test parts is higher similar to the uncoated test bits.

- Figure 2. Displays convective heat transfer coefficient for 5 mm spacing copper and aluminum test parts, and is found to be 12.51 W / m^2 K and 13.23 W / m^2 K respectively.
- Basing on figure 2, It is obvious that the heat transfer rate in aluminum is 5.4 per cent higher than in the copper test component. With improved fineness spacing the transmission of heat from radiation in the aluminum test component is more similar to the transmission of convective heat.

TABLE 1
RECORD OF SURFACE AND AIR TEMPERATURE [12]

Micro-fin Material	Time Duration in hours	Fin Spacing [mm]	Surface Temperature T_{fin} [K]	Air Temperature T_s [K]
Aluminum	1	3.75	111.5	53.8
	2	3.75	120.1	62.9
	3	3.75	130.4	73.7
	4	3.75	140.7	81.7
Aluminium	1	5	151.2	82.3
	2	5	159.9	91.7
	3	5	170	101.1
	4	5	177.7	101.1
Aluminium (with coat Panting)	1	3.75	144.1	101.1
	2	3.75	149.1	109.8
	3	3.75	154.2	113.7
	4	3.75	157.1	115.9
Aluminium (with coat Panting)	1	5	156.3	110.5
	2	5	171.9	122.8
	3	5	176.9	129.9
	4	5	179.4	137.2
Copper	1	3.75	149.2	93.1
	2	3.75	156.8	105.2
	3	3.75	173.8	119.3
	4	3.75	176.1	120.8
Copper	1	5	131.2	92.1
	2	5	149.5	110.9
	3	5	156.3	118.8
	4	5	161.2	124.5
Copper with Aluminium Paint coating	1	3.75	53.6	115.2
	2	3.75	163.2	124.3
	3	3.75	171.5	133.4
	4	3.75	191.4	137.8
Copper with Aluminium Paint coating	1	5	140.9	112.5
	2	5	156.2	123.4
	3	5	165.2	137.5
	4	5	181.3	148.4

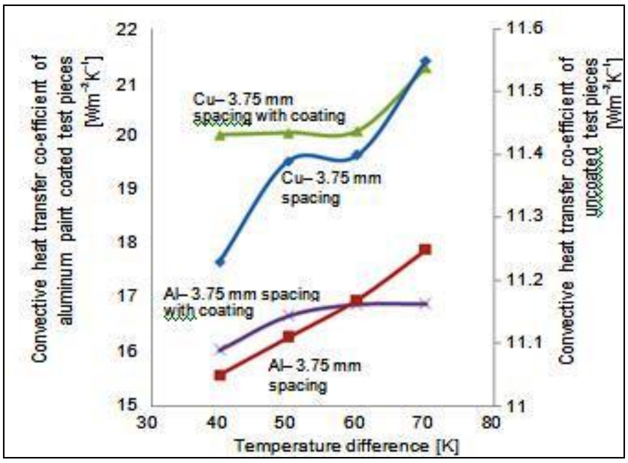

Figure 1. Convective heat transfer coefficient plotted against the temperature difference at 3.75 mm spacing [12]

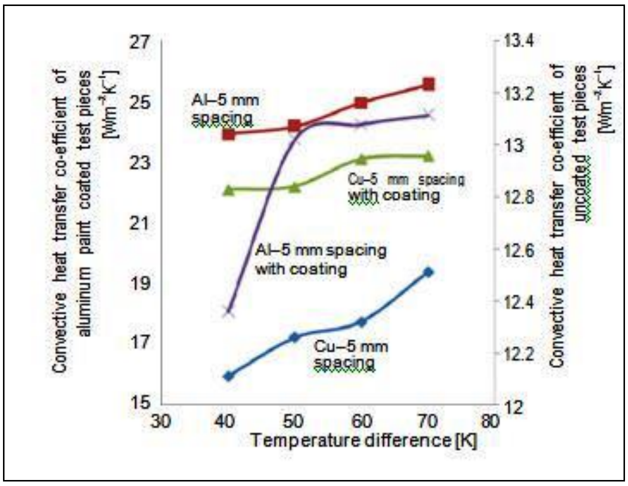

Figure 2. Convective heat transfer coefficient plotted against the temperature difference at 5 mm spacing [12]

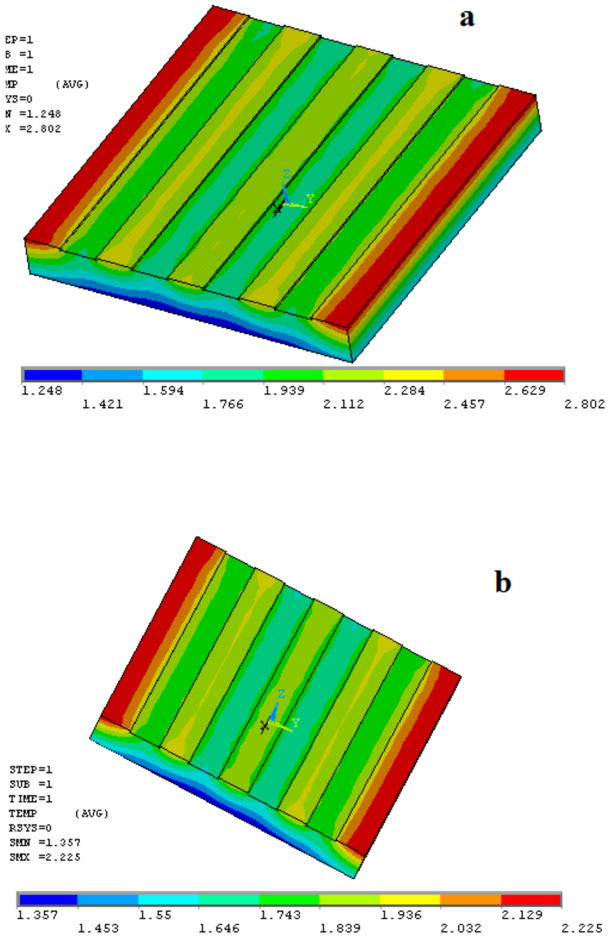

Figure 3. Convective heat transfer coefficient distribution on the painted test pieces in ANSYS (a) Al, (b) Cu [12]

IV. Conclusion

Copper and aluminium coated test components' convective heat transfer coefficients have been calculated. Paint-coated copper and paint-coated aluminium have convective heat transfer coefficients of 21.29 W/m^2 K and 16.90 W/mK, respectively, for 3.75 mm finish spacing. The 5 mm fin spacing paint-coated aluminium test components had the maximum convective heat transfer coefficient of 24.54 W / m^2 K, according to the results. The 5 mm fin spacing paint coated aluminium test components had the greatest convective heat transfer coefficient of 24.54 W / m^2 K. This indicates that the painting enhances the heat transfer capacity of aluminium by 49 percent when compared to metal without painting.

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